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April 1st, 2010 Renesas Electronics Corporation

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MOS FIELD EFFECT TRANSISTOR $\mu PA2590$

N- AND P-CHANNEL MOSFET FOR SWITCHING

DESCRIPTION

The μ PA2590 is N- and P-channel MOSFETs designed for DC/DC converters and power management applications of portable equipments.

N- and P-channel MOSFETs are assembled in one package, to contribute minimize the equipments.

FEATURES

- 4.5 V drive available
- Low on-state resistance

N-channel $R_{DS(on)1} = 50 \text{ m}\Omega \text{ MAX}.$ (VGs = 10 V, ID = 2 A) $R_{DS(on)2} = 83 \text{ m}\Omega \text{ MAX}.$ (VGs = 4.5 V, ID = 2 A)P-channel $R_{DS(on)1} = 72 \text{ m}\Omega \text{ MAX}.$ (VGs = -10 V, ID = -2 A) $R_{DS(on)2} = 105 \text{ m}\Omega \text{ MAX}.$ (VGs = -4.5 V, ID = -2 A)

- Built-in gate protection diode
- Small and surface mount package (8-pin VSOF (2429))

ORDERING INFORMATION

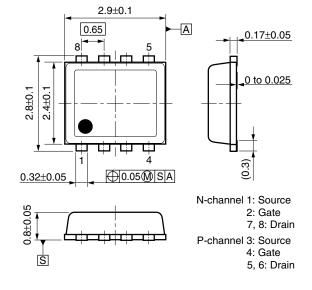
PART NUMBER	LEAD PLATING	PACKING	PACKAGE		
μΡΑ2590Τ1Η-Τ1-ΑΤ ^{Νote}		8 mm embossed taping			
μΡΑ2590Τ1Η-Τ2-ΑΤ ^{Note}	Pure Sn	3000 p/reel	8-pin VSOF (2429)		

Note Pb-free (This product does not contain Pb in the external electrode and other parts.)

Marking: 2590

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Document No. G19217EJ1V0DS00 (1st edition) Date Published May 2008 NS Printed in Japan



PACKAGE DRAWING (Unit: mm)

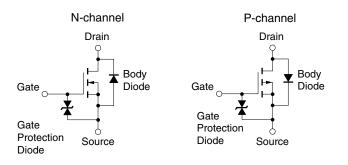
ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

PARAMETER	SYMBOL	N-CHANNEL	P-CHANNEL	UNIT	
Drain to Source Voltage (V _{GS} = 0 V)	VDSS	30	-30	V	
Gate to Source Voltage (V _{DS} = 0 V)	V _{GSS}	±20	∓20	V	
Drain Current (DC)	ID(DC)	±4.5	7 4.5	А	
Drain Current (pulse) Note1	D(pulse)	±18	∓18	А	
Total Power Dissipation (1 unit, 5 s) Note2	P _{T1}	1.5	W		
Total Power Dissipation (2 units, 5 s)	P _{T2}	1.2	W		
Channel Temperature	Tch	150	°C		
Storage Temperature	Tstg	–55 to	°C		

Notes 1. PW \leq 10 μ s, Duty Cycle \leq 1%

2. Mounted on FR-4 board of 25.4 mm x 25.4 mm x 0.8 mmt

EQUIVALENT CIRCUIT



- **Remark** The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.
- Caution This product is electrostatic-sensitive device due to low ESD capability and should be handled with caution for electrostatic discharge.

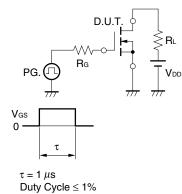
ELECTRICAL CHARACTERISTICS (TA = 25°C)

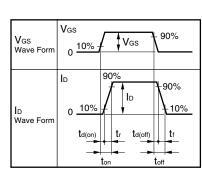
N-channel MOSFET

CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	IDSS	V _{DS} = 30 V, V _{GS} = 0 V			1	μA
Gate Leakage Current	lgss	V _{GS} = ±16 V, V _{DS} = 0 V			±10	μA
Gate to Source Cut-off Voltage	V _{GS(off)}	V _{DS} = 10 V, I _D = 1 mA	1.0		2.5	v
Forward Transfer Admittance Note	Yfs	V _{DS} = 10 V, I _D = 2 A	1			S
Drain to Source On-state Resistance Note	RDS(on)1	V _{GS} = 10 V, I _D = 2 A		38	50	mΩ
	RDS(on)2	V _{GS} = 4.5 V, I _D = 2 A		48	83	mΩ
Input Capacitance	Ciss	V _{DS} = 10 V,		310		pF
Output Capacitance	Coss	V _{GS} = 0 V,		65		pF
Reverse Transfer Capacitance	Crss	f = 1.0 MHz		27		pF
Turn-on Delay Time	td(on)	V _{DD} = 15 V, I _D = 2 A,		6		ns
Rise Time	tr	V _{GS} = 10 V,		2.8		ns
Turn-off Delay Time	td(off)	R _G = 6 Ω		15		ns
Fall Time	tr			2.4		ns
Total Gate Charge	QG	V _{DD} = 24 V, V _{GS} = 10 V,				
		I _D = 4.5 A		6.6		nC
Body Diode Forward Voltage Note	VF(S-D)	IF = 4.5 A, VGS = 0 V		0.9		V

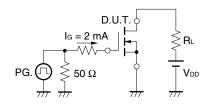
Note Pulsed

TEST CIRCUIT 1 SWITCHING TIME





TEST CIRCUIT 2 GATE CHARGE

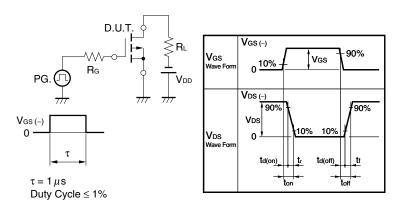


P-channel MOSFET

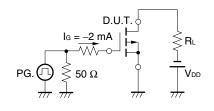
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	Ibss	V _{DS} = -30 V, V _{GS} = 0 V			-1	μA
Gate Leakage Current	lgss	V _{GS} = ∓16 V, V _{DS} = 0 V			∓10	μA
Gate to Source Cut-off Voltage	VGS(off)	V _{DS} = −10 V, I _D = −1 mA	1.0		2.5	v
Forward Transfer Admittance Note	y fs	V _{DS} = -10 V, I _D = -2 A	1			S
Drain to Source On-state Resistance Note	RDS(on)1	V _{GS} = −10 V, I _D = −2 A		56	72	mΩ
	RDS(on)2	V _{GS} = −4.5 V, I _D = −2 A		75	105	mΩ
Input Capacitance	Ciss	V _{DS} = -10 V,		310		pF
Output Capacitance	Coss	V _{GS} = 0 V,		78		pF
Reverse Transfer Capacitance	Crss	f = 1.0 MHz		65		pF
Turn-on Delay Time	t d(on)	V_{DD} = -15 V, I _D = -2 A,		6.5		ns
Rise Time	tr	V _{GS} = -10 V,		3.5		ns
Turn-off Delay Time	td(off)	R _G = 6 Ω		33		ns
Fall Time	tr			26		ns
Total Gate Charge	Q _G	V_{DD} = -24 V, V_{GS} = -10 V,				
		I _D = -4.5 A		7.5		nC
Body Diode Forward Voltage Note	V _{F(S-D)}	IF = -4.5 A, VGS = 0 V		0.95		V

Note Pulsed

TEST CIRCUIT 1 SWITCHING TIME

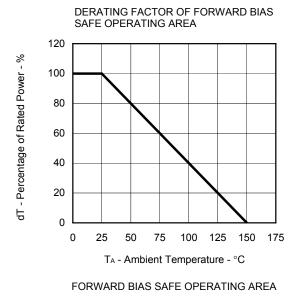


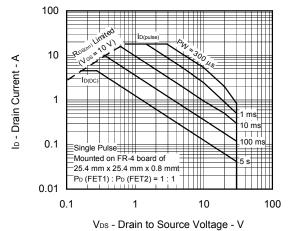
TEST CIRCUIT 2 GATE CHARGE

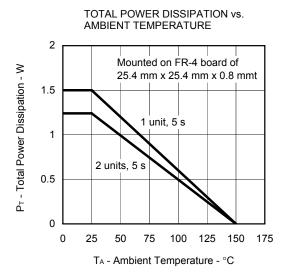


TYPICAL CHARACTERISTICS (T_A = 25°C)

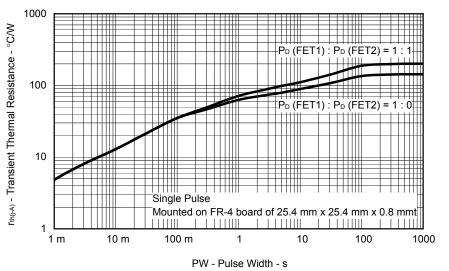
(1) N-channel MOSFET



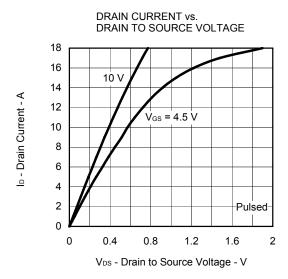




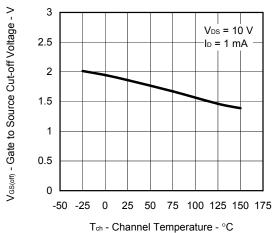
TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



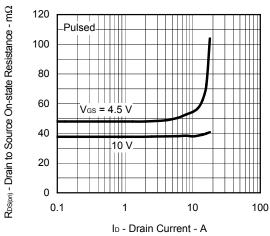
Data Sheet G19217EJ1V0DS



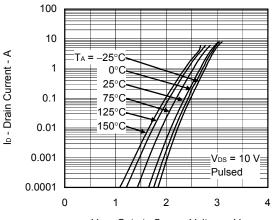




DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT

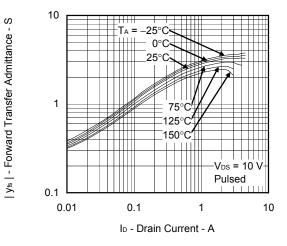


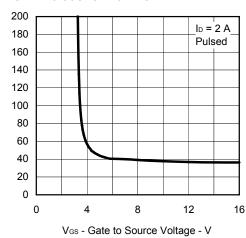
FORWARD TRANSFER CHARACTERISTICS



V_{GS} - Gate to Source Voltage - V

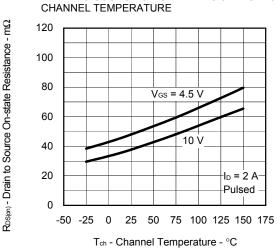
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT





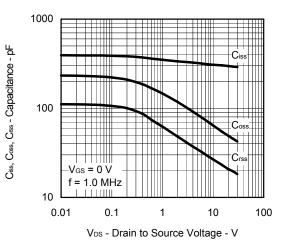
DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE

 $R_{DS(on)}$ - Drain to Source On-state Resistance - $m\Omega$

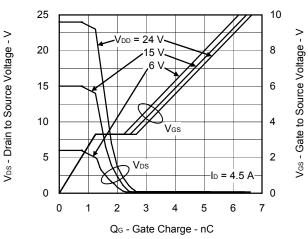




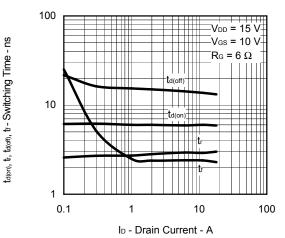
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE

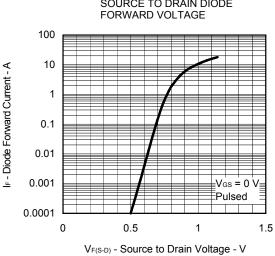


DYNAMIC INPUT/OUTPUT CHARACTERISTICS









SOURCE TO DRAIN DIODE

(2) P-channel MOSFET

-0.1

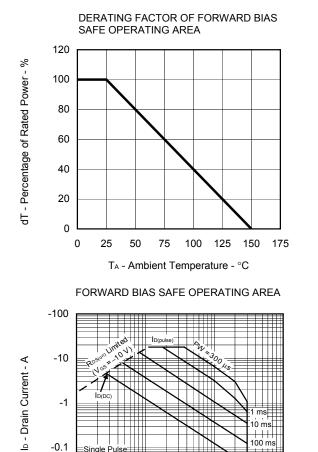
-0.01 -0.1

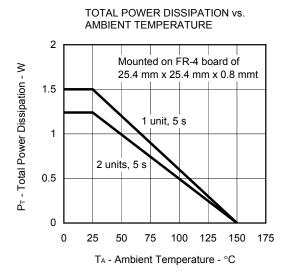
Single Pulse Mounted on FR-4 board of Mounted on FR-4 board of 25.4 mm x 25.4 mm x 0.8 mmt

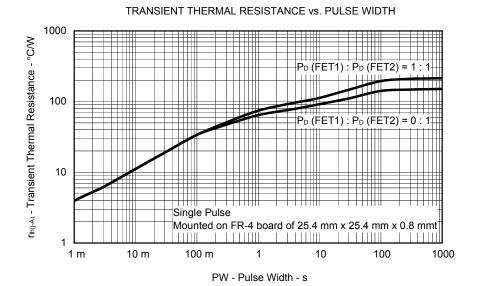
PD (FET1) : PD (FET2) = 1 : 1

-1

VDS - Drain to Source Voltage - V







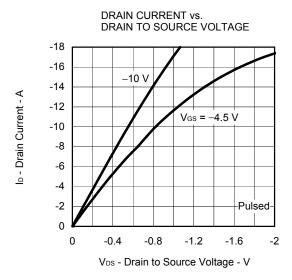
100 m

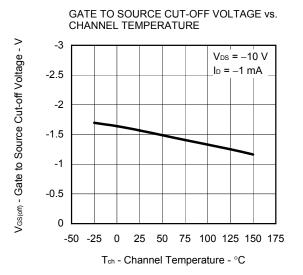
-100

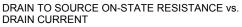
5 s

-10

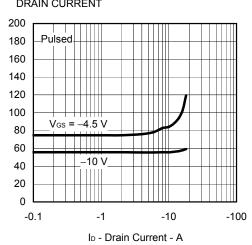
Data Sheet G19217EJ1V0DS



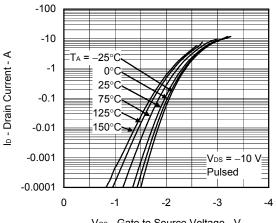




 $R^{\rm DS(on)}$ - Drain to Source On-state Resistance - $m\Omega$

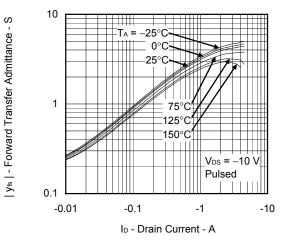


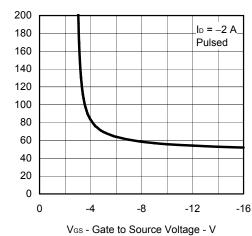




 $V_{\mbox{\scriptsize GS}}$ - Gate to Source Voltage - V

FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT

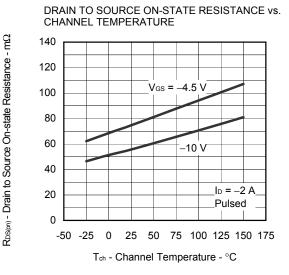




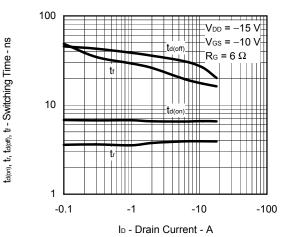
DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE

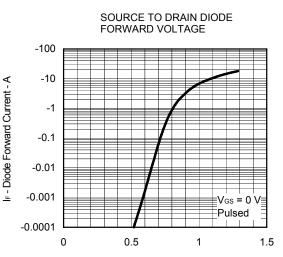
Data Sheet G19217EJ1V0DS

 $D_{S(on)}$ - Drain to Source On-state Resistance - $m\Omega$



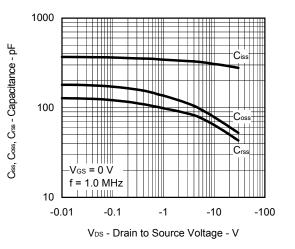
SWITCHING CHARACTERISTICS



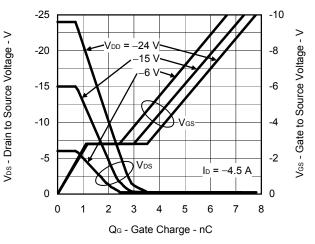


VF(S-D) - Source to Drain Voltage - V

CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



DYNAMIC INPUT/OUTPUT CHARACTERISTICS



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